

0492-2504-Q/Final (1)/TCS

ABSTRACT OF THE DISCLOSURE

5 An apparatus for removing fluorinated and chlorinated compounds contained in waste gas streams from semiconductor etch and deposition processes. The apparatus has a treatment chamber in which a plurality of liquid films are formed to absorb the fluorinated and chlorinated compounds
10 contained in the waste gas streams that pass through the liquid films. The apparatus includes a tank for receiving the mixture of the absorbed fluorinated and chlorinated compounds and the liquid, and a dehumidifying device for stabilizing and dehumidifying the humidified waste gas
15 streams.